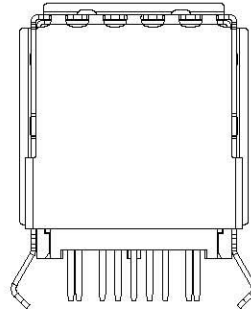
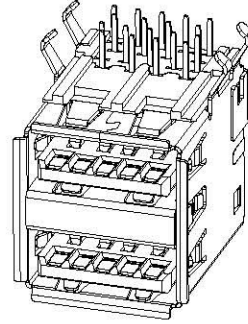
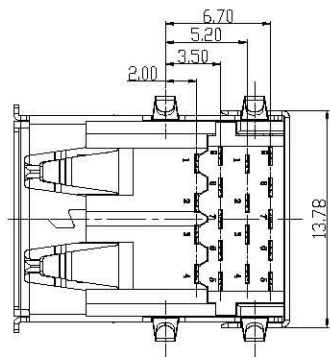
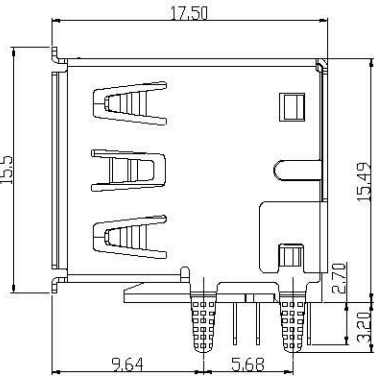


PCB LAYOUT REFERENCE



Remark:

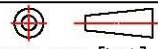
1.MATERIAL:

- 1.1 Housing:thermoplastic plastics.
- 1.2 terminals:Copper Alloy
- 1.3 Front Shell:Copper Alloy/SPCC.  
Middle Shell:SPCC

2.characteristics:

- 2.1 Rating Voltage : 30V AC.
- 2.2 Rating Current:PIN1&PIN4(Vbus&Correponding ground PIN)  
1.8A MAX Other PINS 0.25A min.
- 2.3 Contact Resistance:PIN1&PIN4:30 mΩ MAX. Other PINS: 50 mΩ
- 2.4 Insulation Resistance:100 MΩ MIN.
- 2.5 Withstanding Voltage:AC 100V between adjacent contacts
- 2.6 Mating force: 3.57Kgf MAX(35N MAX)
- 2.7 Extraction force:1Kgf Min(9.8N Min)
- 2.8 Life test:1500Cycles MIN.
- 2.9 Temperature Range: -30℃~+80℃.

## L&X 深圳市连欣科技有限公司

<b>TOLERANCE:</b> X.X ±0.30 X.XX ±0.25 X.XXX ±0.15 X.' ±2' X.X' ±0.5'	<b>DRAWN BY :</b> 陈一鸣	<b>DATE :</b> 2014-02-23	<b>PART NAME:</b> USB3.0 AF 双层90°	
	<b>CHECKED BY:</b> 马跃	<b>DATE :</b> 2014-02-23	<b>PART NO.</b> XUBF-1800-0610	<b>MOLD NO.</b> /
 <b>UNIT: mm [inch]</b> <b>SCALE:1:1 SIZE: A4</b>	<b>APPROVED BY:</b> 邱国夷	<b>DATE :</b> 2014-02-23	<b>DRAW NO:</b> USBA15010610	<b>SHEET NO.</b> 1 OF 1